

#### Features:

- 1. Package in 8mm tape on 7" diameter reel.
- 2. Compatible with automatic placement equipment.
- 3. Compatible with infrared and vapor phase reflow solder process.
- 4. 2.00mm×1.80mm SMT LED, 1.10mm thickness.
- 5. Low power consumption.
- 6. Color: Hyper Red & Pure Green.
- 7. Bi-color type.
- 8. The product itself will remain within RoHS compliant Version.

### Descriptions:

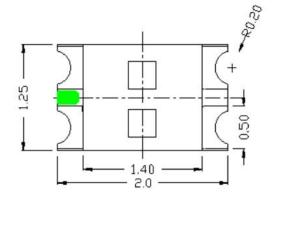
- 1. The PCB 0805 SMD Taping is much smaller than lead frame type components, thus enable smaller higher packing density, reduced storage space and finally smaller equipment to be obtained.
- 2. Besides, light Weight makes them ideal for miniature applications, etc.

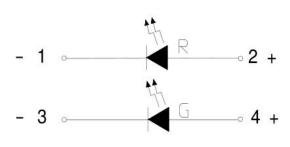
## Applications:

- 1. Automotive: Backlighting in dashboard and switch.
- 2. Telecommunication: Indicator and backlighting in telephone and fax.
- 3. Flat backlight for LCD, switch and symbol.

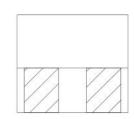
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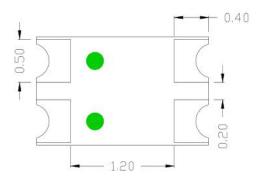
## **◆** Package Dimension:

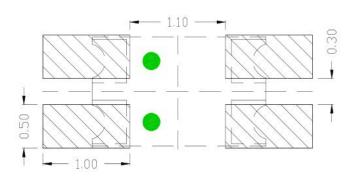












Part No	Chip Material		Lens Color	Source Color	
DL-PCB0805SRPGC	SR	AlGaInP	Motor Cloor	Hyper Red	
	PG	InGaN	Water Clear	Pure Green	

### Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ±0.10mm (.004") unless otherwise noted.
- 3. Specifications are subject to change without notice.

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# ♦ Absolute Maximum Ratings at Ta=25°C

Parameters		Symbol	Max.	Unit	
Davier Dissipation	Hyper Red	<b>D</b> D	60	mW	
Power Dissipation	Pure Green	PD	95		
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)		IFP	100	mA	
Continuous Forward Current		IF	25	mA	
Reverse Voltage		VR	5	V	
Operating Temperature Range		Topr	-40°C to +80°C		
Storage Temperature Range		Tstg	-40°C to +85°C		
Soldering Temperature		Tsld	260°C for 5 Seconds		

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## ◆ Electrical Optical Characteristics at Ta=25 °C

Parameters	Symbol	Emitting Color	Min.	Тур.	Max.	Unit	Test Condition	
Luminous Intensitu	IV	Hyper Red	100	170		mad	IF=20mA (Note 1)  IF=20mA (Note 2)  Measurement @Peak	
Luminous Intensity	IV	Pure Green	200	320		mcd		
Viewing Angle	20	Hyper Red		D	IF=20mA			
	2θ <sub>1/2</sub>	Pure Green		130		Deg	(Note 2)	
Peak Emission Wavelength	3.5	Hyper Red		632			Measurement	
	λр	Pure Green		520		nm		
Dominant Wavelength		Hyper Red		624			IF=20mA (Note 3)	
	λd	Pure Green		525		nm		
Spectral Line Half-Width	^ <b>3</b>	Hyper Red		20			IF=20mA	
	Δλ	Pure Green		35		nm		
Forward Voltage		Hyper Red	1.60	2.00	2.40	.,	IF=20mA	
	VF	Pure Green	2.80	3.40	3.80	V		
De como Como di	15	Hyper Red			4.0		V 5V	
Reverse Current	IR	Pure Green			10	μΑ	V <sub>R</sub> =5V	

#### Notes:

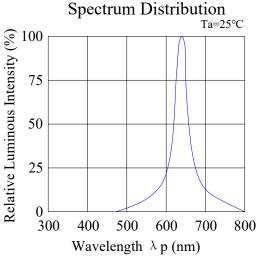
- 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
  - 2.  $\theta_{1/2}$  is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength ( $\lambda d$ ) is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.

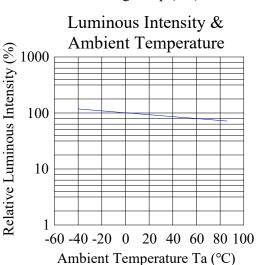
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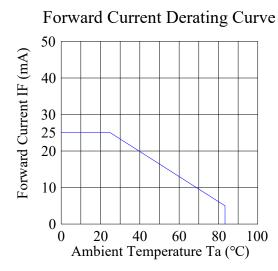
## ◆ Typical Electrical / Optical Characteristics Curves

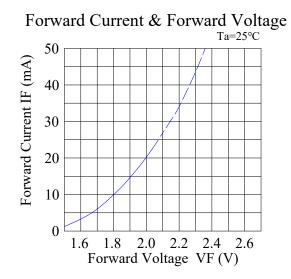
### (25℃ Ambient Temperature Unless Otherwise Noted)

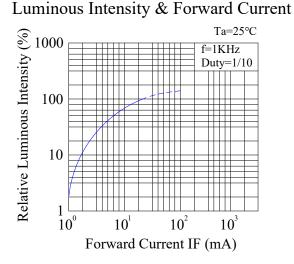
### **Hyper Red:**

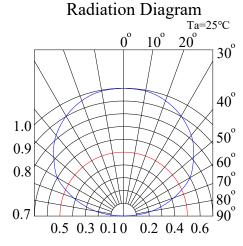




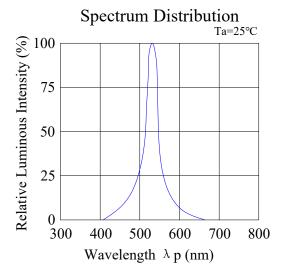




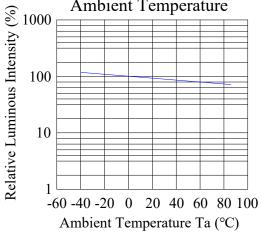




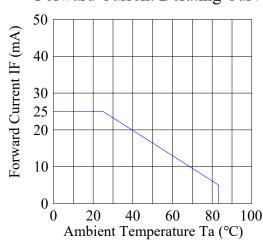
#### **Pure Green:**



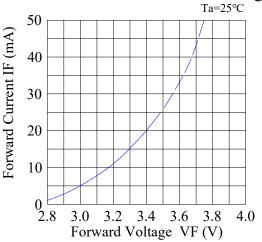
# Luminous Intensity & **Ambient Temperature**



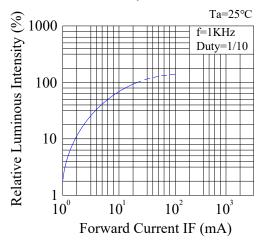
## Forward Current Derating Curve



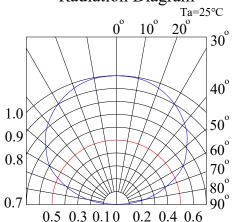
## Forward Current & Forward Voltage



### Luminous Intensity & Forward Current



### Radiation Diagram



## **♦** Reliability Test Items And Conditions:

The reliability of products shall be satisfied with items listed below:

Confidence level: 90%.

LTPD: 10%.

### 1) Test Items and Results:

No.	Test Item	Test Hours/Cycles	Test Conditions	Sample Size	Ac/Re
1	Resistance to Soldering Heat	6 Min	Tsld=260±5℃, Min. 5sec	25pcs	0/1
2	Thermal Shock	300 Cycles	H: +100°C 5min ∫ 10 sec L: -10°C 5min	25pcs	0/1
3	Temperature Cycle	300 Cycles	H: +100°C 15min ∫ 5min L: -40°C 15min	25pcs	0/1
4	High Temperature Storage	1000Hrs.	Temp: 100°C	25pcs	0/1
5	DC Operating Life	1000Hrs.	IF=20mA	25pcs	0/1
6	Low Temperature Storage	1000Hrs.	Temp: -40°C	25pcs	0/1
7	High Temperature/ High Humidity	1000Hrs.	85℃/85%RH	25pcs	0/1

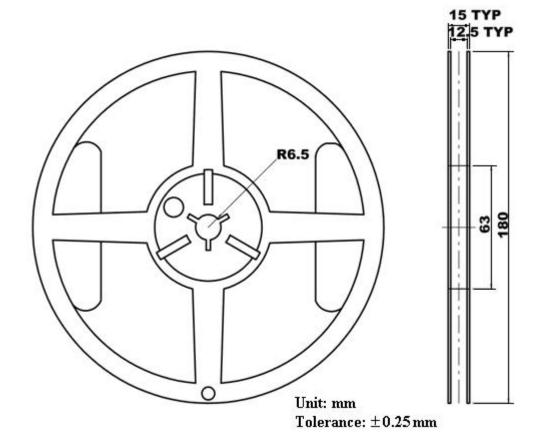
## 2) Criteria for Judging the Damage:

lton	Cumbal			or Judgment	
Item	Symbol	l Test Conditions	Min	Max	
Forward Voltage	VF	IF=20mA		F.V.*)×1.1	
Reverse Current	IR	VR=5V		F.V.*)×2.0	
Luminous Intensity	IV	IF=20mA	F.V.*)×0.7		

\*) F.V.: First Value.

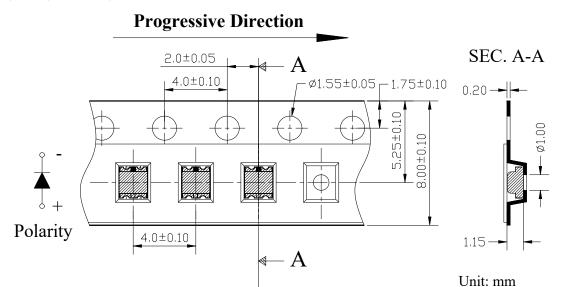
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### **♦** Reel Dimensions:



## **Carrier Tape Dimensions:**

Loaded quantity 3000PCS per reel.



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Tolerance: ±0.10mm

## Please read the following notes before using the datasheets:

#### 1. Over-current-proof

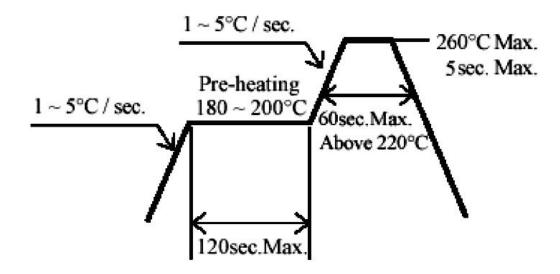
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

#### 2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 The LEDs should be used within a year.
- 2.4 After opening the package, the LEDs should be kept at 30°C or less and 70%RH or less.
- 2.5 The LEDs should be used within 168 hours (7 days) after opening the package.
- 2.6 If the moisture adsorbent material (silica gel) has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 60±5°C for 24 hours.

#### 3. Soldering Condition

3.1 Pb-free solder temperature profile.



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

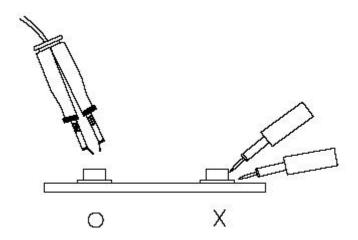
#### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 260°C for 5 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

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### 5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



#### 6. Caution in ESD

Static Electricity and surge damages the LED. It is recommended to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

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